/ Descriptions

1.0A UMB
1.0A Surface Mount Glass Passivated Bridge Rectifier,UMB thin package.

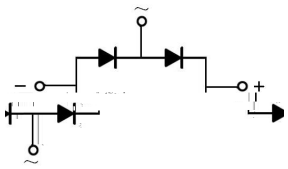
/ Features

100V~1000V 1.0A
Glass Passivated Chip Junction, High Surge Current Capability, Reverse Voltage :100 to 1000V, Forward Current:1.0A, Designed for Surface Mount Application. HF product.

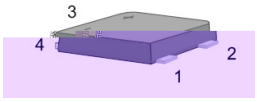
/ Applications

.
General purpose.

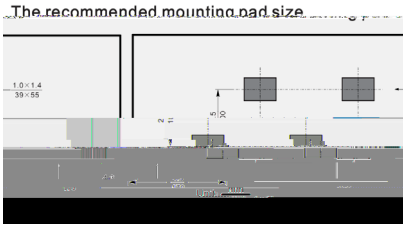
/ Equivalent Circuit



/ Pinning



PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)



/ Marking

See Marking Instructions.

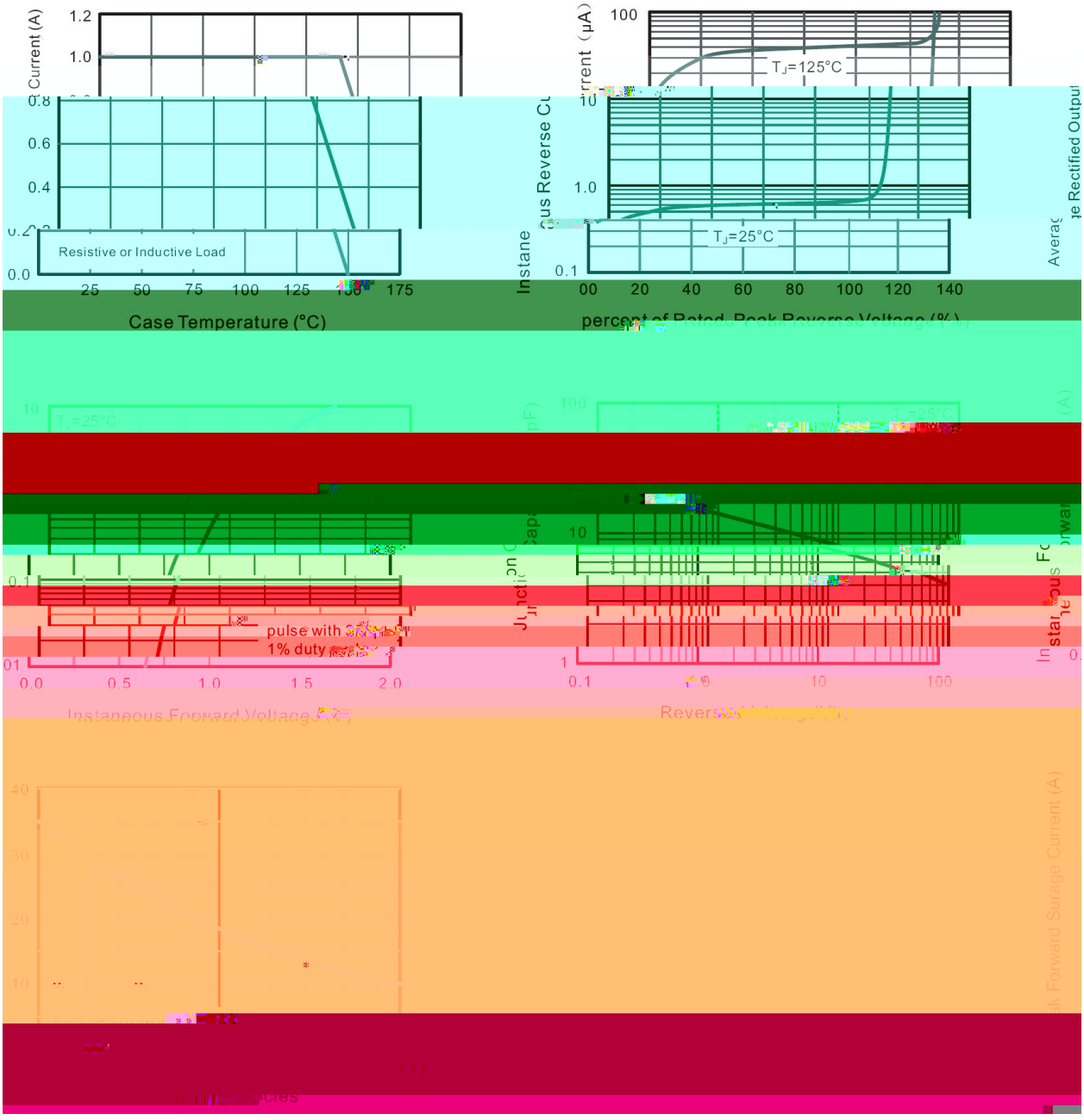
Parameter	Symbol	Rating						Unit
		UM1B-10	UM2B-10	UM4B-10	UM6B-10	UM8B-10	UM10B-10	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current at Ta = 115	I_o	1.0						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	35						A
Typical Junction Capacitance Note1	C_i	13						pF
Typical Thermal Resistance Note2	R_{JA} R_{JC}	85 25						/W
Operating and Storage Temperature Range	T_j,T_{stg}	-55~150						

Note:

1. Measured at 1MHz and applied reverse voltage of 4 V D.C.
2. P.C.B. mounted with 4x1.5 x1.5 (3.81x3.81cm) copper pad areas.

Parameter	Symbol	Test Conditions	Rating	Unit
Forward Voltage per element	V_F	I_F=1.0A	1.1	V
Maximum DC Reverse Current at Maximum DC Blocking Voltage	I_R	T_a=25	5.0	A
		T_a=125		

/ Electrical Characteristic Curve

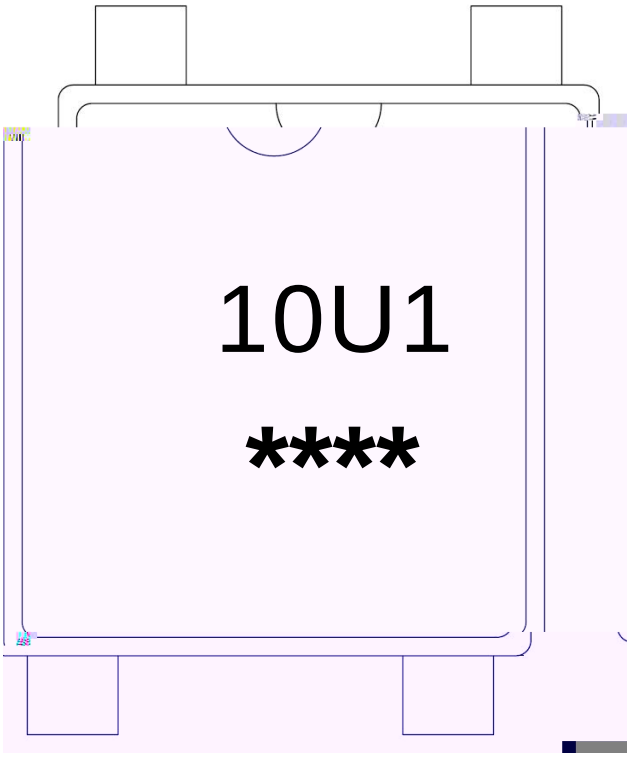


/ Marking Instructions

Marking

Type number	Marking code
UM1B-10	10U1
UM2B-10	10U2
UM4B-10	10U4
UM6B-10	10U6
UM8B-10	10U8
10U10	UM10B-10

/ Marking Instructions



10U1

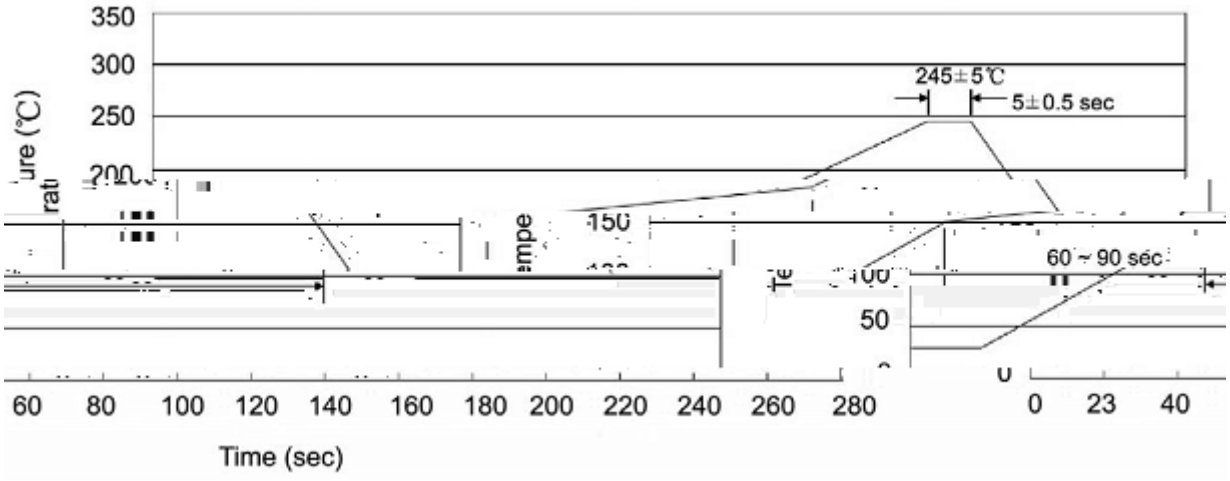
**** 1 * 3 *

Note:

10U1 Product Type Code

**** Lot No. Code The 1st * means:YM Code The last 3 * means:little Lot No Code

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

1	25 150	60 90sec;	1.Preheating:25~150	, Time:60~90sec.
2	245±5	5±0.5sec;	2.Peak Temp.:245±5	, Duration:5±0.5sec.
3	2 10 /sec.		3. Cooling Speed: 2~10 /sec.	

/ Resistance to Soldering Heat Test Conditions

260±5	10±1 sec.	Temp.:260±5	Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension			(unit mm^3)		
	5000	2	10,000	5	50,000	13 ×16	340	340 40	350	350 230	

/ Notices